## ration and power of at

As a below named inventor. I hereby declare that: my residence, post office address and citizenship are as stated below

next to my name: that I believe I a	im the original, tirst and sole inventor (i	i only one name is listed be	low) or an original,
tirst and joint inventor (if plural na	imes are listed bel w) of the subject ma	tter which is claimed and fo	ir which a patent is
sought on the invention entitled:	HESIVE COMPOSITION AND JOIN	ING METHOD UTILIZING	G
TF	E ADHESIVE COMPOSITION		
the specification of which is A atta	ched and/or  was filed onand was amended on (if applica	as Ap	plication Serial No.
International (PCT) application I hereby state that I have reviewe as amended by any amendment refer I acknowledge the duty to disclo	No. PCT/JP00/05694 filed August 24, 20 d and understand the contents of the aboute to above.  se information which is material to the experience of the expe	00 and as amended on April ove identified specification, in	ncluding the claims,
or inventor's certificate listed below	ns, §1.50(a).  Denefits under Title 35, United States Co  v and have also identified below any fore  the application on which priority is claimed	ign application for patent or	lication(s) for paten inventor's certificate
COUNTRY	APPLICATION NUMBER	DATE OF FILING	PRIORITY CLAIMED
JAPAN	241599/1999	08/27/1999	MYES ONO
	· ·		CIYES CINO
□ Se	e attached list for additiona	nrior foreign appli	cations

JAPAN	241599/1999	08/27/1999	MAEZ DWO
			Q YES QNO
	attached list for additional		
	Title 35, United States Code, §120 of an		
insofar as the subject matter of each	h of the claims of this application is not	disclosed in the prior Unite	d States application

in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

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	APPLICATION NUMBER	DATE OF FILING	STATUS (Pewned, Pending, Abandoned)	_
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I hereby appoint the following attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Law Offices of Townsend & Banta: Donald E. Townsend, Registration No. 22,069; Teresa J. Banta, Registration No. 34,543; and Donald E. Townsend, Ir., Reg. No. 43,198.... Please address all correspondence to the Law Offices of Townsend & Banta, Suite 500, 1225 Eye Street, N.W., Washington, D.C. 20005

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued there n.

FULL NAME OF SOLE OR FIRST INVENTOR	HIVENTOR'S SIGNATURE	STAD
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